

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

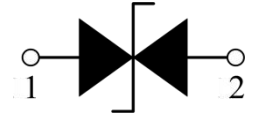
Features

- Capacitance: 15pF(typ.)
- Reverse Working Voltage: 5V
- IEC 61000-4-2 (ESD Air): ±25KV
- IEC 61000-4-2 (ESD Contact): ±25KV
- IEC 61000-4-5 (Lightning 8/20µs): 8A

Pin Description



Schematic Diagram



Applications

DFN1006

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

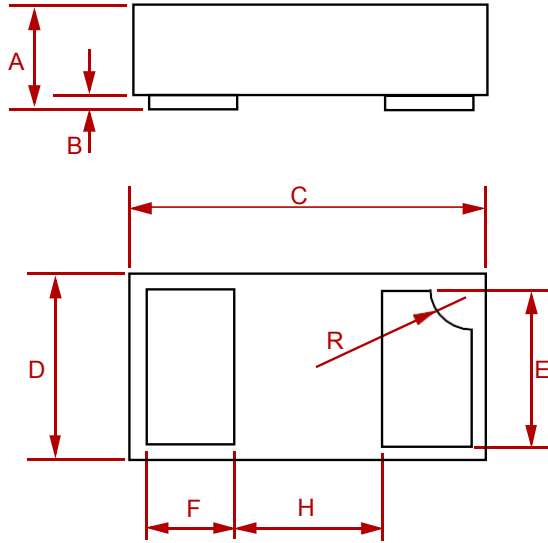
Limiting Values(T_A = 25 °C, unless otherwise specified)

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|---------------------------------|----------------------------------|-----|-----|------|
| V _{ESD} | Electrostatic Discharge Voltage | IEC 61000-4-2; Contact Discharge | - | ±25 | kV |
| | | IEC 61000-4-2; Air Discharge | - | ±25 | kV |
| P _{PP} | Peak Pulse Power | t _P = 8/20 µs | - | 80 | W |
| I _{PPM} | Rated Peak Pulse Current | t _P = 8/20 µs | - | 8 | A |
| T _A | Ambient Temperature Range | - | -55 | 125 | °C |
| T _{stg} | Storage Temperature Range | - | -55 | 150 | °C |

Electrical Characteristics(T_A = 25 °C, unless otherwise specified)

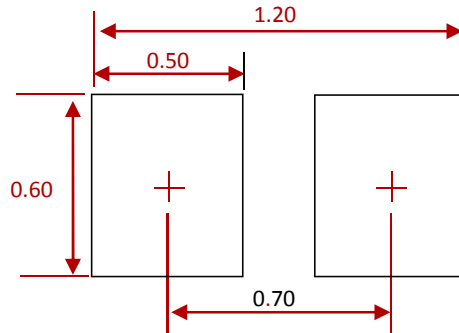
| Symbol | Parameter | Conditions | Min | Typ. | Max | Unit |
|------------------|-------------------------|---|-----|------|-----|------|
| V _{RWM} | Reverse Working Voltage | T _A = 25 °C | - | - | 5.0 | V |
| V _{BR} | Breakdown Voltage | I _R = 1mA; T _A = 25 °C | 5.6 | 6.5 | 8.4 | V |
| I _R | Reverse Leakage Current | V _{RWM} = 5V; T _A = 25 °C | - | - | 0.1 | µA |
| V _C | Clamping Voltage | I _{PP} =1A, t _P =8/20µs | - | - | 6 | V |
| | | I _{PP} =8A, t _P =8/20µs | - | - | 10 | V |
| C _J | Junction Capacitance | V _R = 0V, f = 1 MHz | - | 15 | 18 | pF |

PACKAGE MECHANICAL DATA



| Dim | Inches | | Millimeters | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.0125 | 0.02 | 0.32 | 0.52 |
| B | 0.000 | 0.002 | 0.00 | 0.05 |
| C | 0.037 | 0.043 | 0.95 | 1.080 |
| D | 0.022 | 0.027 | 0.55 | 0.680 |
| E | 0.016 | 0.024 | 0.40 | 0.60 |
| F | 0.008 | 0.012 | 0.20 | 0.30 |
| H | 0.015Typ. | | 0.40Typ. | |
| R | 0.001 | 0.005 | 0.05 | 0.15 |

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

| P/N | PKG | QTY |
|-----------------|---------|-------|
| PESD5V0S1BLN-MS | DFN1006 | 10000 |

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